

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3398683

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MICHAEL R. FUNK	10/16/2014
RECEIVING PARTY DATA	
Name:	UNITED STATES OF AMERICA AS REPRESENTED BY THE ADMINISTRATOR OF THE NATIONAL AERONAUTICS AND SPACE ADMINISTRATION
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State/Country:	D.C.
Postal Code:	20546
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14513813
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ATTORNEY DOCKET NUMBER:	LAR-18334-1
NAME OF SUBMITTER:	YVETTE D. MARDIS
SIGNATURE:	/s/ Yvette D. Mardis
DATE SIGNED:	06/16/2015
Total Attachments: 1	
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Assignment to the Government (by Government Employee)

Title of Invention: Single-Step, Solvent-Free, Catalyst-Free Preparation of Holey Carbon Allotropes

Inventor(s): YI LIN, JAE-WOO KIM, JOHN W. CONNELL, MICHAEL R. FUNK, CAROLINE CAMPBELL

NASA Case No.: LAR-18334-1 Application No.: 14/513,813 Filing Date*: 10/14/2014

WHEREAS, the parties to this Assignment and Agreement are the undersigned inventor(s) and the United States Government (hereafter Government), as represented by the Administrator of the National Aeronautics and Space Administration;

WHEREAS, the making of this Assignment and Agreement is in accordance with 37 CFR Part 501; and

WHEREAS, the undersigned inventor(s) has (have) executed, on the date(s) indicated below, an application for United States Patent on the above-entitled invention.

NOW THEREFORE, in consideration of employment by the Government, the undersigned hereby:

1. Assign to the Government my (our) full and exclusive right in and to said invention within the United States of America, its territories and possessions, and my (our) entire right, title and interest in and to said application, and any corresponding continuation or divisional application(s) and any patent(s) that may issue therefrom.

2. Agree to grant to the Government my (our) full and exclusive foreign rights in and to said invention, in accordance with 37 CFR 501.9(d), including rights of priority under the International Convention of Paris (1883), as amended. If the Government chooses not to file an application in any foreign country, I (we) may request rights in that country, in accordance with 37 CFR 501.9(d), and such rights will be subject to the reservation to the Government of a nonexclusive, irrevocable, royalty-free license in the invention with power to grant licenses for all governmental purposes. The terms of such reservation will appear, where practicable, in any foreign patent which may issue on such invention.

3. Agree, at the expense of the Government, (a) to execute any document for, (b) to deliver any requested information to, and (c) to cooperate in any manner with the Government in order to allow the Government to protect any interest transferred by this Assignment and Agreement.

*4. Authorize and request the attorneys of record in the application to insert the application number and filing date above when required.

(Signature of Inventor)

JOHN W. CONNELL

(Inventor's Typed Name)

Michael R. Funk

(Signature of Inventor)

MICHAEL R. FUNK

(Inventor's Typed Name)

(Date Assignment Executed)

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